Texas Instruments 12500 TI Boulevard, MS 8640, Dallas, Texas 75243

# PCN20250923000.1
# Qualification of additional Assembly sites for select HSOIC devices
# Change Notification / Sample Request

**Date:** September 23, 2025
**To:** MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

## 20250923000.1
## Attachment: 1

## Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

| DEVICE | CUSTOMER PART NUMBER |
|---|---|
| TPS5430DDARG4 | TPS5430DDAR |
| TPS2421-2DDA | TPS2421-2DDA |
| TPS5430DDAR | TPS5430DDAR |
| TPS2421-2DDAR | TPS2421-2DDAR |

Technical details of this Product Change follow on the next page(s).

| | | | |
|---|---|---|---|
| **PCN Number:** | PCN#20250923000.1 | **PCN Date:** | September 23, 2025 |
| **Title:** | Qualification of additional Assembly sites for select HSOIC devices | | |
| **Customer Contact:** | Change Management Team | **Dept:** | Quality Services |
| **Proposed 1st Ship Date:** | December 22, 2025 | **Sample requests accepted until:** | November 22, 2025* |

***Sample requests received after November 22, 2025 will not be supported.**

**Change Type:**

| | | | | | |
|---|---|---|---|---|---|
| ☒ | Assembly Site | ☐ | Design | ☐ | Wafer Bump Material |
| ☐ | Assembly Process | ☐ | Data Sheet | ☐ | Wafer Bump Process |
| ☒ | Assembly Materials | ☐ | Part number change | ☐ | Wafer Fab Site |
| ☒ | Mechanical Specification | ☐ | Test Site | ☐ | Wafer Fab Material |
| ☒ | Packing/Shipping/Labeling | ☐ | Test Process | ☐ | Wafer Fab Process |

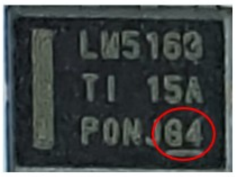
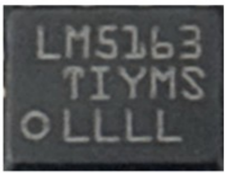
## PCN Details

**Description of Change:**

Texas Instruments Incorporated is announcing the qualification of additional Assembly sites for devices listed below in the product affected section. Construction information and all assembly sites are as follows:

| HSOIC Build Sites | |
|---|---|
| **Assembly Sites** | FMX, ASESH, HNA, TAI |
| **Mount Compound** | 4223772 |
| | 4147858 |
| | 4224264 |
| | SID#EY2000030 |
| | SID#EY1000063 |
| | SID#400728 |
| | 4208458 |
| | 4042504 |
| **Mold compound** | 4211880 |
| | SID#EN2000509 |
| | SID#EN20000519 |
| | SID#450042 |
| | SID#450207 |
| | 4211649 |
| | 4205443 |
| **Lead finish** | NiPdAu |
| **MSL** | MSL2 |
| **Package Outline drawing** | DDA0008J, DDA0008E, DDA0008B |

**Topside marking**

| | Current | Additional |
|---|---|---|
| Pin 1 ID | Stripe | Dot |
| ECAT value | With | Without |
| Topside Marking sample |  |  |

Qual details are provided in the Qual Data Section.

## Reason for Change:

Continuity of Supply

## Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

There are changes on the Thermal pad dimension on the Package Outline drawing. See updated Package Outline drawing and / or the Supporting Data Packet for more details on the changes.

## Impact on Environmental Ratings

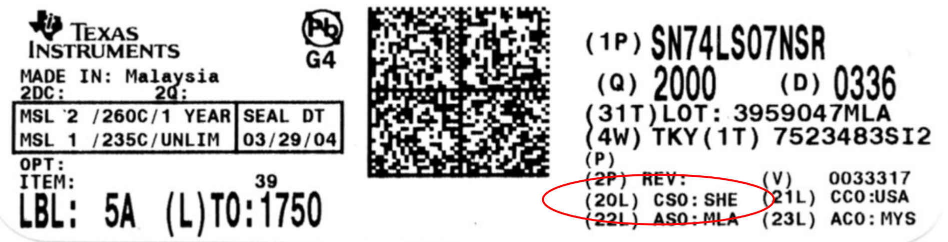
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

| RoHS | REACH | Green Status | IEC 62474 |
|---|---|---|---|
| ☒ No Change | ☒ No Change | ☒ No Change | ☒ No Change |

## Changes to product identification resulting from this PCN:

| Assembly Site | Assembly Site Origin (22L) | Assembly Country Code (23L) | Assembly City |
|---|---|---|---|
| ASESH | ASH | CHN | Shanghai |
| HNA | HNT | THA | Ayutthaya |
| TAI | TAI | TWN | Chung Ho,<br>New Taipei City |
| FMX | MEX | MEX | Aguascalientes |

Sample product shipping label (not actual product label)



TEXAS INSTRUMENTS
G4
MADE IN: Malaysia
2DC:
2Q:
MSL 2 /260C/1 YEAR SEAL DT
MSL 1 /235C/UNLIM 03/29/04
OPT:
ITEM: 39
LBL: 5A (L)TO:1750
(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T)LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

## Product Affected:

| | | | |
|---|---|---|---|
| DRV8872DDAR | TPS2421-2DDAR | TPS5430DDARG4 | TPS5431DDARG4 |
| TPS2421-1DDA | TPS5430DDA | TPS5431DDA | |
| TPS2421-1DDAR | TPS5430DDAG4 | TPS5431DDAG4 | |
| TPS2421-2DDA | TPS5430DDAR | TPS5431DDAR | |

# HSOIC Qualification Report

## Data Displayed as: Number of lots / Total sample size / Total failed

| | Stress Test | Duration | FMX<br>UCC27301AQDDARQ1<br>LM5163DDA | ASESH<br>LMR38020SDDA<br>OPA462IDDA |
|---|---|---|---|---|
| TC | Temperature Cycling -65/150C | 500 Cycles | 3/231/0 | 3/231/0 |
| HAST | Biased HAST 130C/85%RH | 96 hours | 3/231/0 | 3/231/0 |
| HTSL | High Temp. Storage Bake 150C | 1000 hours | 3/231/0 | - |
| HTSL | High Temp. Storage Bake 170C | 420 hours | - | 3/231/0 |
| AC | Autoclave 121C | 96 hours | 3/231/0 | - |
| UHAST | Unbiased HAST 130C/85%RH | 96 hours | - | 3/231/0 |
| SD | Solderability | 8 Hour Steam age or 155C Dry Bake | 3/66/0 | 3/66/0 |
| MQ | Manufacturability | - | Pass | Pass |

| | Stress Test | Duration | HNA<br>OPA454AIDDA<br>OPA2211AIDDA | TAI<br>TPA1517DWP<br>OPA564AQDWPRQ1 |
|---|---|---|---|---|
| TC | Temperature Cycling -65/150C | 500 Cycles | 3/231/0 | 3/231/0 |
| HAST | Biased HAST 130C/85%RH | 96 hours | 3/231/0 | 3/231/0 |
| HTSL | High Temp. Storage Bake 170C | 420 hours | 3/231/0 | 3/231/0 |
| AC | Autoclave 121C | 96 hours | - | 3/231/0 |
| UHAST | Unbiased HAST 130C/85%RH | 96 hours | 3/231/0 | - |
| SD | Solderability | 8 Hour Steam age or 155C Dry Bake | 3/66/0 | 3/66/0 |
| MQ | Manufacturability | - | Pass | Pass |

Devices LMR38020SDDA, LM5163DDA, OPA454AIDDA, OPA2211AIDDA, TPA1517DWP, OPA462IDDA, UCC27301AQDDARQ1 qualified at L2-260C MSL rating
Device OPA564AQDWPRQ1 qualified at L3-260C MSL rating

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, and HTSL, as applicable
- The following are equivalent HTSL options based on activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status: Qualified Pb-Free (SMT) and Green

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a ‘product qualification family’ for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled “QBS Process” (for wafer fab process), “QBS Package” (for assembly process) and “QBS Product” (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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